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[73] Proprietor 專利所有人

CONNECTOR SYSTEMS TECHNOLOGY N.V., Julianaplein  
22, Willemstad, Curacao, Netherlands Antilles 荷屬安的列斯  
群島

[72] Inventor 發明人

ABE, HIROSHI

NARITA, HIROSHI

TAKAHASHI, RYOSUKE

[74] Agent and / or address for service 代理人及/或送達地址

Deacons Graham & James, 3/FI., Alexandra House, Central,  
Hong Kong  
的近律師行，香港中環歷山大廈 3 樓

[54] CONNECTOR APPARATUS FOR IC PACKAGES 集成電路封裝連接設備